



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IFX27001TF V33	<b>Issued</b>	24. February 2022
<b>MA#</b>	MA005700974		
<b>Package</b>	PG-TO252-3-11	<b>Weight*</b>	379.58 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.924	0.77	0.77	7703	7703
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		170	
	non noble metal	iron	7439-89-6	0.215	0.06		567	
	non noble metal	copper	7440-50-8	215.017	56.64	56.72	566467	567204
wire	non noble metal	aluminium	7429-90-5	0.163	0.04	0.04	428	428
encapsulation	organic material	carbon black	1333-86-4	0.267	0.07		704	
	plastics	epoxy resin	-	12.286	3.24		32368	
	inorganic material	silicondioxide	60676-86-0	120.992	31.88	35.19	318755	351827
leadfinish	non noble metal	tin	7440-31-5	3.740	0.99	0.99	9853	9853
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	239	240
solder	non noble metal	tin	7440-31-5	0.092	0.02		243	
	noble metal	silver	7440-22-4	0.115	0.03		304	
	non noble metal	lead	7439-92-1	4.407	1.16	1.21	11609	12156
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.05	5.06	50523	50589
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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